

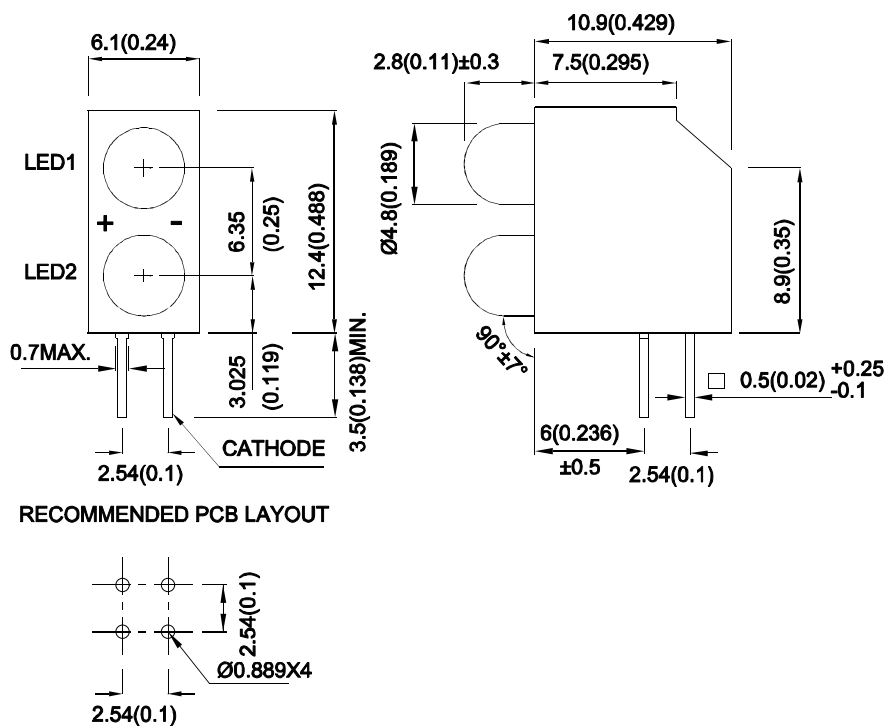
### Features

- Pre-trimmed leads for pc board mounting.
- Colors can be mixed in a single housing.
- Black case enhances contrast ratio.
- Wide viewing angle.
- High reliability - life measured in years.
- Housing UL rating:94V-0.
- Housing material: type 66 nylon.
- RoHS compliant.

### Description

The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

### Package Dimensions



#### Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.25(0.01") unless otherwise noted.
3. Lead spacing is measured where the leads emerge from the package.
4. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.



## Selection Guide

Part No.	Emitting Color (Material)	Lens Type	Iv (mcd) [2] @ 10mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
WP73EB/2YDA	Yellow (GaAsP/GaP)	Yellow Diffused	6	15	60°

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity / luminous Flux: +/-15%.
3. Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

## Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Emitting Color	Typ.	Max.	Units	Test Conditions
λ <sub>peak</sub>	Peak Wavelength	Yellow	590		nm	I <sub>F</sub> =10mA
λ <sub>D</sub> [1]	Dominant Wavelength	Yellow	588		nm	I <sub>F</sub> =10mA
Δλ <sub>1/2</sub>	Spectral Line Half-width	Yellow	35		nm	I <sub>F</sub> =10mA
C	Capacitance	Yellow	20		pF	V <sub>F</sub> =0V;f=1MHz
V <sub>F</sub> [2]	Forward Voltage	Yellow	1.95	2.5	V	I <sub>F</sub> =10mA
I <sub>R</sub>	Reverse Current	Yellow		10	uA	V <sub>R</sub> = 5V

Notes:

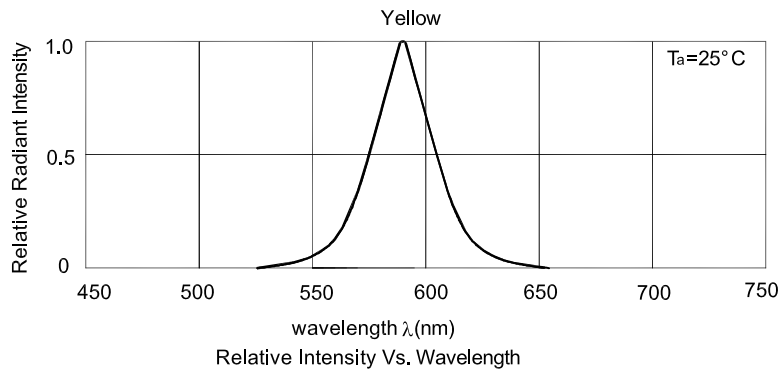
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.
3. Wavelength value is traceable to the CIE127-2007 compliant national standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

## Absolute Maximum Ratings at TA=25°C

Parameter	Values	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	140	mA
Reverse Voltage	5	V
Operating/Storage Temperature	-40°C To +85°C	
Lead Solder Temperature [2]	260°C For 3 Seconds	
Lead Solder Temperature [3]	260°C For 5 Seconds	

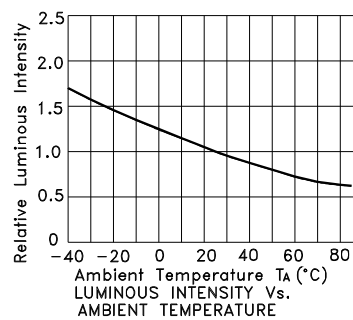
Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.



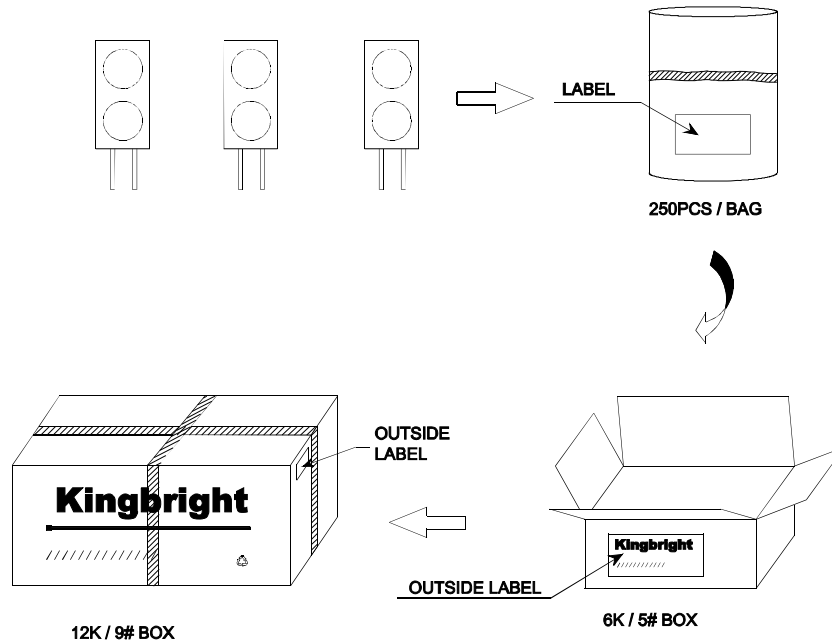
Yellow

WP73EB/2YDA



## PACKING & LABEL SPECIFICATIONS

WP73EB/2YDA



<h1>Kingbright</h1>				
P/NO: WP73EBxxx				
QTY: 250 pcs	Q.C.			
S/N: XXXX	<table border="1"> <tr> <td>Q C</td> </tr> <tr> <td>xxxxxxx</td> </tr> <tr> <td>PASSED</td> </tr> </table>	Q C	xxxxxxx	PASSED
Q C				
xxxxxxx				
PASSED				
CODE: XXX				
LOT NO:				
RoHS Compliant				

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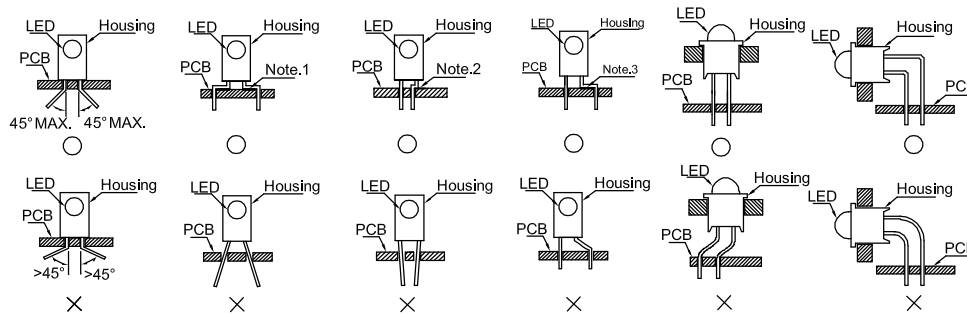
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2. The part number, type, and specifications mentioned in this document are subject to future change and improvement without notice. Before production usage customer should refer to the latest datasheet for the updated specifications.
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## PRECAUTIONS

### 1. Storage conditions:

- Avoid continued exposure to the condensing moisture environment and keep the product away from rapid transitions in ambient temperature.
- LEDs should be stored with temperature  $\leq 30^{\circ}\text{C}$  and relative humidity  $< 60\%$ .
- Product in the original sealed package is recommended to be assembled within 72 hours of opening. Product in opened package for more than a week should be baked for 30 (+10/-0) hours at  $85 \sim 100^{\circ}\text{C}$ .

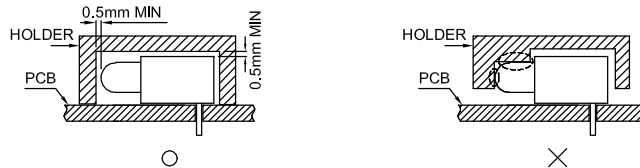
### 2. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.



" O " Correct mounting method " X " Incorrect mounting method

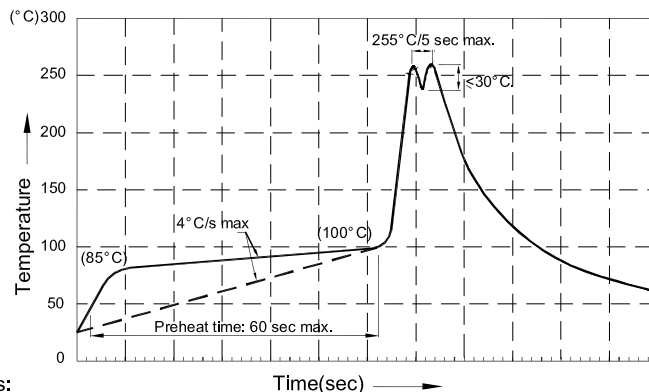
Note 1-3: Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

### 3. During soldering, component covers and holders should leave clearance to avoid placing damaging stress on the LED during soldering.



- The tip of the soldering iron should never touch the lens epoxy.
- Through-hole LEDs are incompatible with reflow soldering.
- If the LED will undergo multiple soldering passes or face other processes where the part may be subjected to intense heat, please check with Kingbright for compatibility.

### 7. Recommended Wave Soldering Profiles:



Notes:

- Recommend pre-heat temperature of  $105^{\circ}\text{C}$  or less (as measured with a thermocouple attached to the LED pins) prior to immersion in the solder wave with a maximum solder bath temperature of  $260^{\circ}\text{C}$
- Peak wave soldering temperature between  $245^{\circ}\text{C} \sim 255^{\circ}\text{C}$  for 3 sec (5 sec max).
- Do not apply stress to the epoxy resin while the temperature is above  $85^{\circ}\text{C}$ .
- Fixtures should not incur stress on the component when mounting and during soldering process.
- SAC 305 solder alloy is recommended.
- No more than one wave soldering pass.